

RD Number: RD055

RD Title: TB67S109AFTG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VCC	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
2	C_VM2	1	0.1μF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
3	C_VRFA	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
4	C_VRFB	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
5	C_VM1	1	100μF 50V	—	—	Electrolytic capacitor		
6	C_VDD	1	10μF 25V	—	—	Electrolytic capacitor		
7	C_OSCM	0	Socket pin	—	—	Socket pin		✓
8	C_OSCM	0	270pF 25V	—	—	Leaded capacitor	2.54mm pitch	✓
9	C_OSCM	1	270pF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
10	C_OAP	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
11	C_OAM	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
12	C_OBM	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
13	C_OBP	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
14	CON1	1	Connector	—	—	Connector 4P 2.5		
15	CON2	0	Connector	—	—	Connector 2P 2.5		✓
16	CON3	0	Connector	—	—	Connector 2P 2.5		✓
17	CON4	0	Connector	—	—	Connector 3P 2.5		✓
18	CON5	0	Connector	—	—	Connector 3P 2.5		✓
19	OUT_A-	1	Check terminal	—	—	Check pin		
20	OUT_A+	1	Check terminal	—	—	Check pin		
21	OUT_B-	1	Check terminal	—	—	Check pin		
22	OUT_B+	1	Check terminal	—	—	Check pin		
23	RSA	1	Check terminal	—	—	Check pin		
24	RSB	1	Check terminal	—	—	Check pin		
25	VCC	1	Check terminal	—	—	Check pin		

26	VDD	1	Check terminal	—	—	Check pin		
27	VM	1	Check terminal	—	—	Check pin		
28	NC	0	Check terminal	—	—	Check pin		✓
29	38	1	Check terminal	—	—	Check pin		
30	39	1	Check terminal	—	—	Check pin		
31	VREFB	1	Check terminal	—	—	Check pin		
32	42	1	Check terminal	—	—	Check pin		
33	OSCM	1	Check terminal	—	—	Check pin		
34	44	1	Check terminal	—	—	Check pin		
35	45	1	Check terminal	—	—	Check pin		
36	46	1	Check terminal	—	—	Check pin		
37	47	1	Check terminal	—	—	Check pin		
38	2	1	Check terminal	—	—	Check pin		
39	3	1	Check terminal	—	—	Check pin		
40	4	1	Check terminal	—	—	Check pin		
41	GND1	1	Check terminal	—	—	Check pin		
42	GND2	1	Check terminal	—	—	Check pin		
43	GND3	1	Check terminal	—	—	Check pin		
44	GND4	1	Check terminal	—	—	Check pin		
45	GND5	1	Check terminal	—	—	Check pin		
46	GND6	1	Check terminal	—	—	Check pin		
47	GND7	1	Check terminal	—	—	Check pin		
48	JP_VRF1	1	Pin header 2P	—	—	Jumper 2.54mm pitch		
49	JP_VRF1	1	Jump socket	—	—	Short pin		
50	JP_VRF2	1	Pin header 2P	—	—	Jumper 2.54mm pitch		
51	JP_VRF2	1	Jump socket	—	—	Short pin		
52	JP_VCC	1	Pin header 2P	—	—	Jumper 2.54mm pitch		
53	JP_VCC	1	Jump socket	—	—	Short pin		
54	R_ID	0	100kΩ 0.25W	—	—	Leaded resistor	2.54mm pitch	✓
55	R_MOUT	1	100kΩ 0.25W	—	—	Leaded resistor	2.54mm pitch	
56	R_LOUT	1	100kΩ 0.25W	—	—	Leaded resistor	2.54mm pitch	
57	R_OSCM	0	Socket pin	—	—	Socket pin		✓

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